



40th International Spring Seminar on Electronics Technology



ISSE 2017

Sofia, Bulgaria, May 10–14, 2017

40th International Spring Seminar on Electronics Technology

„High-Tech Electronics for a Better Tomorrow - Theoretical and Practical Aspects“

2nd CALL FOR PAPERS

Dear Colleagues,

It is a great pleasure to invite you to submit an extended abstract / full paper to the International Spring Seminar on Electronics Technology organized by Department of Microelectronics, Faculty of Electronic Engineering and Technologies, Technical University of Sofia that will take place in Bulgaria, Sofia on May 10–14, 2017.

Aims of the Conference

- Electronics, Electronics Manufacturing, Micro- and Nanoelectronics, Research, Development, Manufacturing, Testing and Teaching;
- International cooperation and student exchanges;
- Forum for junior and senior scientists from Europe and other continents.



Through keynote speeches by outstanding scholars and practitioners, in oral sessions, posters presentations and exhibitions, the Conference will reflect an overview of the latest developments in electronics technologies. The topics of ISSE 2017 will ensure an exchange of scientific information and opinions in a field with impressive dynamics, considering the technological progress, theoretical and practical aspects of the research. This conference provides opportunities for the senior and young researchers, as well as representatives to the academia and industry, to exchange new ideas, to establish research or business relations and to find partners for future collaboration. We hope that the conference will constitute significant contribution to the knowledge in this up to date scientific field.



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Topics of Interest

- A. New Materials, Components and Processes
- B. Thermal Management
- C. Advanced Packaging and Interconnection Technologies
- D. Testing, Reliability and Quality Management
- E. Process Modelling and Simulation
- F. Environmental and Ecological Effects in Electronics Technology
- G. Nanotechnology, Nanomaterials and Nanoelectronics
- H. Signal Integrity and Electromagnetic Compatibility
- I. Sensors, Actuators and Microsystems
- J. Educational and Information Technologies in Electronics Manufacturing
- K. Discrete and Integrated Components

Official Language

English

Conference Venue

Vitosha Park Hotel, Rosario Str., No 1,
Sofia 1700, Bulgaria (vitoshaparkhotel.com)

Important Due Dates

You are kindly requested to send your abstract to e-mail isse2017@tu-sofia.bg as attachment in MS Word (Version 2003 or later) and PDF format.

Submission of Abstracts: February 3rd, 2017

Notification of Acceptance: March 17th, 2017

Early bird registration until: March 31st, 2017

Submission of Full-length Papers: April 14th, 2017

Registration ultimate DEADLINE: April 14th, 2017

Publication of Papers

All accepted and presented papers will be included in the conference proceedings and forwarded to the IEEE Xplore Digital Library (ieeexplore.ieee.org). All papers will be checked by the IEEE iThenticate-Test. The papers must be original and not previously published, and avoid inclusion of commercial content.



ISSE 2017 Conference Organizers

General Chair: Heinz Wohlrabe (Dresden University of Technology, Germany)

Secretary of ISSE: Oliver Krammer (Budapest University of Technology and Economics, Hungary)

Technical Program Committee (TPC) Chair: Johann Nicolics (Vienna University of Technology, Austria)

Conference Chair: Anna Stoyanova (Technical University of Sofia, Bulgaria)

Board of Organizers: Philipp Philippov – Honoured Chair, Nencho Nenov, Nikolay Dodev, Rossen Radonov, Valentin Tsenev, Nikolay Hinov, Ivailo Pandiev, Mariya Aleksandrova, Elitsa Gieva, Dimitar Nikolov, Mariya Spasova.

Please, find further information for authors including the abstract and paper templates and other important hints on our website: <http://isse2017.tu-sofia.bg/>

We are looking forward to seeing you in Sofia in May 2017!

Best regards,
Anna Andonova Stoyanova



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